

**For Immediate Release**

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## **Maxtek Adds Rapid Prototyping Services for Faster Design Validation & Time-to-Production**

BEAVERTON, Ore., August 6, 2009 – Maxtek Components Corporation, a Tektronix, Inc. company and a provider of turnkey packaging services for microelectronics, today announced the introduction of Rapid Prototyping Services. The new services, a result of industry and voice-of-customer research, are designed to support the need for faster validation of IC and package designs and speed the transition to full production.

For equipment manufacturers in the defense, measurement, medical and communications industries, custom integrated circuits are a frequent and critical part of their next-generation products just as timely delivery for these systems is vital to remaining competitive. With this growing time-to-market pressure, being able to reduce the time it takes to validate IC and package designs and move into the prototype phase of a project is increasingly valuable to system manufacturers and their development programs.

Maxtek's Rapid Prototyping Services were specifically developed to address this need for prototype speed, offering customers a path to rapidly validate their ASIC designs by providing access to advanced interconnect capabilities and a low-cost means of identifying issues—all of which is intended to reduce the design-to-prototype timeline. Additionally, and unlike dedicated prototype facilities, Maxtek provides customers with access to a highly-experienced engineering team as well as a complete manufacturing line capable of supporting full-rate production of low-volume (1k to 100k parts per year) for high-performance or high-reliability IC packages and modules.

“Our new Rapid Prototyping Service shows Maxtek’s commitment to meeting our customers’ needs and enabling their success,” said Tom Buzak, President, Maxtek Components Corporation. “Whether you’re discussing the design-validation timeline or overall time-to-production, the positive impact to a development project’s schedule of having prototypes in as little as three days can’t be overstated and we’re proud to offer this capability.”

### **Three Levels of Rapid Prototyping Services**

In evaluating the varying requirements of customers within the medical, communications, defense and measurement markets, Maxtek identified three services levels for rapid prototyping—BGA Build-to-Print, Advanced Build-to-Print and Process Evaluation Build—primarily based upon device complexity and the associated resource requirements and lead-time.

Entry-level prototyping (i.e., the least complex) is offered via Maxtek’s BGA Build-to-Print service, assembling JEDEC-standard Ball Grid Arrays in as little as three business days. For more complex packaging needs that may require additional production time, Maxtek created the Advanced Build-to-Print and Process Evaluation Build service levels to provide additional solutions and flexibility for custom requirements.

For further information on Maxtek’s Rapid Prototyping Services, call 1-800-462-9835, e-mail [technology@maxtek.com](mailto:technology@maxtek.com) or visit [www.maxtek.com](http://www.maxtek.com).

### **About Maxtek Components Corporation**

Maxtek, a Tektronix company, provides turnkey IC packaging and microelectronic module services to meet the demanding performance and reliability requirements of defense, medical, measurement and communications applications. With over 39 years of experience in creating custom components – from high-speed data converters and flip-chip BGAs to optical transceivers and RF modules – Maxtek works as an extension of our customers’ product development teams to deliver quality microelectronics. Headquartered in Beaverton, Oregon, Maxtek can be found on the web at [www.maxtek.com](http://www.maxtek.com).